



Material Content Data Sheet



Sales Product Name		TLE5205-2G		Issued		27. September 2017		
MA#		MA001209576						
Package		PG-TO263-7-1		Weight*		1537.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.039	0.72	0.72	7178	7178
leadframe	non noble metal	iron	7439-89-6	0.810	0.05		526	
	inorganic material	phosphorus	7723-14-0	0.243	0.02		158	
	non noble metal	copper	7440-50-8	808.613	52.57	52.64	525805	526489
wire	non noble metal	aluminium	7429-90-5	2.557	0.17	0.17	1663	1663
encapsulation	organic material	carbon black	1333-86-4	8.786	0.57		5713	
	plastics	epoxy resin	-	96.641	6.28		62841	
	inorganic material	silicondioxide	60676-86-0	480.277	31.23	38.08	312303	380857
leadfinish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8477	8477
plating	non noble metal	nickel	7440-02-0	0.212	0.01		138	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	525804	138
solder	noble metal	silver	7440-22-4	0.232	0.02		151	
	non noble metal	tin	7440-31-5	0.186	0.01		121	
	non noble metal	lead	7439-92-1	8.877	0.58	0.61	5772	6044
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		69	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	106.210	6.91	6.92	69064	69154
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com